Special Issue

Emerging Liquid Alloy Intelligence: From Fundamental to Application Exploration

Message from the Guest Editors

Being a high-fluidity, highly conductive material at room temperature, liquid alloys demonstrate numerous attractive advantages in many aspects, particularly for the deformable smart system in dynamic situations. Potentially, they will be an essential part of future soft intelligence and ultimately serve as an intimate partner of our daily life. We invite original research papers, technical notes and shorter communications that focus on all areas on liquid alloy development at the micro/nanoscale, from fundamental research, including materials, interface, processing and devices, to application exploration, including biology, environment, electromagnetics, agriculture and robots, to contribute to this Special Issue. We are also looking for high-quality comprehensive reviews and perspectives that reference prior interest expressed to the Editorial Office and have received formal approval.

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